Product End-of-Life Disassembly Instructions

Product Category: Calculators

Marketing Name / Model
[List multiple models if applicable.]

HP EliteDesk 800 G2 DM 35W Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>0</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at EL-MF877-01
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screwdriver T15 Torx</td>
<td>12cm~17cm</td>
</tr>
<tr>
<td>Description #2 screwdriver M2 Philips</td>
<td>10cm~15cm</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel
2. Remove HDD and HDD FAN for Dolomite and Hood Sensor
3. Remove system fan
4. Remove heat sink from M/B
5. Remove WLAN Card from M/B
6. Remove ambient sensor fly cable and Speaker cable
7. Remove M/B and battery
8. Remove Memory
9. Remove Rear IO (HDMI/DP/SERIAL) card and M.2 card
10. Remove front bezel

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

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1. Remove access panel
<table>
<thead>
<tr>
<th></th>
<th>Instructions</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Release 1 thumb screw on the access panel as photo1 shown</td>
</tr>
<tr>
<td></td>
<td>Screw spec : T15 Torx</td>
</tr>
<tr>
<td>2</td>
<td>Handle the chassis and push access panel as the direction then remove the access panel as photo2 shown</td>
</tr>
</tbody>
</table>

**Photo1**

**Photo2**

PSG instructions for this template are available at [EL-MF877-01](#).
2. Remove HDD and HDD FAN for Dolomite and Hood Sensor

1. Lift HDD latch up then press HDD the forward for escaping from cage as photo1 shown

2. Pull the connector first then pull HDD SATA FFC cable out of motherboard as photo2 shown
3. Release 3 screws of HDD cage first then remove hood sensor cable from M/B as photo3 shown
Screw spec : T15 Torx

4. Remove hood sensor from HDD cage as photo4 shown

5. HDD FAN
( only Dolomite )
Release 2 screws of HDD cage then turn the hook to unlock the HDD fan in HDD cage as photo5 shown
Screw spec : M2 Philips

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<table>
<thead>
<tr>
<th>Photo3</th>
<th>Photo4</th>
<th>Photo5</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1.png" alt="Photo3" /></td>
<td><img src="image2.png" alt="Photo4" /></td>
<td><img src="image3.png" alt="Photo5" /></td>
</tr>
</tbody>
</table>

**Dolomite**
3. Remove system fan

1. Lift system fan up then remove it as photo1 shown

2. Remove system fan cable from M/B as photo2 shown

Photo1

Photo2
## 4. Remove heat sink from M/B

<p>| | |</p>
<table>
<thead>
<tr>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>1</strong></td>
<td>Release 3 screws by order 3 to 1 to free heat sink from chassis as photo1 shown</td>
</tr>
<tr>
<td></td>
<td>Screw spec : T15 Torx</td>
</tr>
</tbody>
</table>

**Photo1**
5. Remove WLAN Card from M/B

1. Pull out antenna from WLAN card as photo1 shown

2. Release 1 screws from M/B as photo2 shown
   - Screw spec: M2 Philips

3. Remove WLAN card as photo3 shown
6. Remove ambient sensor fly cable and Speaker cable

1. Remove ambient sensor fly cable and SPK cable from M/B as photo1 shown

Photo1

Only Dolomite
7. Remove M/B and battery

1. Release 4 screws by order 4 to 1 to free M/B from chassis as photo1 shown
   Screw spec : T15 Torx

2. Follow the direction to drag M/B out of chassis as photo2 shown

3. Remove battery from M/B by loosing the clip outwards as direction shown

Photo1

Photo2

Photo3

Remove coin battery from MB

PSG instructions for this template are available at EL-MF877-01
8. Remove Memory

1. Release DDR by pressing latches outwards as photo1 shown

2. Remove DDR as photo2 shown
9. Remove Rear IO (HDMI/DP/ SERIAL) card and M.2 card

1. **Rear IO card**
   - Release 2 screws then remove Rear IO card as photo1 shown
   - Screw spec : T15 Torx

2. **M.2 card**
   - Release 1 screws from M/B as photo2 shown
   - Screw spec : M2 Philips

3. Remove M.2 (SSD) card as photo3 shown

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PSG instructions for this template are available at EL-MF877-01
10. Remove front bezel

1. Lift up 3 latches first then pressing 2 latches in the side of front bezel for escaping from chassis as photo1 shown

2. Take out front bezel photo2 shown

Photo1

Photo2

PSG instructions for this template are available at EL-MF877-01